

Ad
cont

11. (New) The multilayered wiring substrate according to claim 10, wherein said conductive layer in said dummy through hole is electrically connected to said conductive layer in any one of said through holes.

IN THE ABSTRACT

Page 23, lines 1-15, please amend the abstract to read as follows:

ABSTRACT

Each wiring layer of a multilayered wiring substrate includes signal wirings disposed in parallel with one another, and dummy wirings disposed at each side parallel to the signal wirings of the signal wiring group made by signal wiring, respectively. The dummy wirings have the same shape as the signal wirings, and are disposed in parallel to the signal wirings at the same intervals as that in the signal wirings. Through holes are formed in the respective clearances among the signal wirings. Dummy through holes having the same shape as the through holes are formed between the dummy wiring and signal wiring. A conductive layer is formed on the inner wall of the through holes. The multilayered wiring substrate is able to reduce or eliminate the delay time difference between signals that propagate along the signal wirings.

REMARKS

Favorable reconsideration of this application as presently amended and in light of the following discussion is respectfully requested.

Claims 1-11 are pending in the present application. Claim 1 has been amended and Claims 7-11 have been added by the present amendment.